

Amendments to the Specification:

Please replace amended paragraph [0023] with the following amended paragraph.

[0023] Moreover, a second preferred embodiment is provided as shown in FIG. 3A. Therein, the under bump metallization structure 306 of this invention according to the second another embodiment may comprise two electrically conductive layers 306a and 306b. A first electrically conductive layer 306a comprises a titanium layer, an aluminum layer; a nickel-vanadium alloy layer [[or]] and a copper layer, and the titanium layer is directly attached to a plurality of bonding pads 304. The bonding pads 304 are made of copper. Alternatively, a first electrically conductive layer 306a may comprise an aluminum layer, a nickel-vanadium alloy layer and a copper layer, and the aluminum layer is directly attached to a plurality of bonding pads 304. In this case, the bonding pads are made of aluminum. In addition, the material of the first electrically conductive layer 306a is selected from the group of aluminum, titanium, titanium-vanadium alloy, titanium-tungsten alloy, copper, nickel-copper alloy, nickel and nickel-vanadium alloy and a second electrically conductive layer 306b mainly comprises tin and nickel wherein the first electrically conductive layer 306a is directly formed on the bonding pads 304 and the second electrically conductive layer 306b is directly connected to the bumps 308. In addition, the thickness of the second electrically conductive layer is ranged from about 50 μm to about 80 μm .